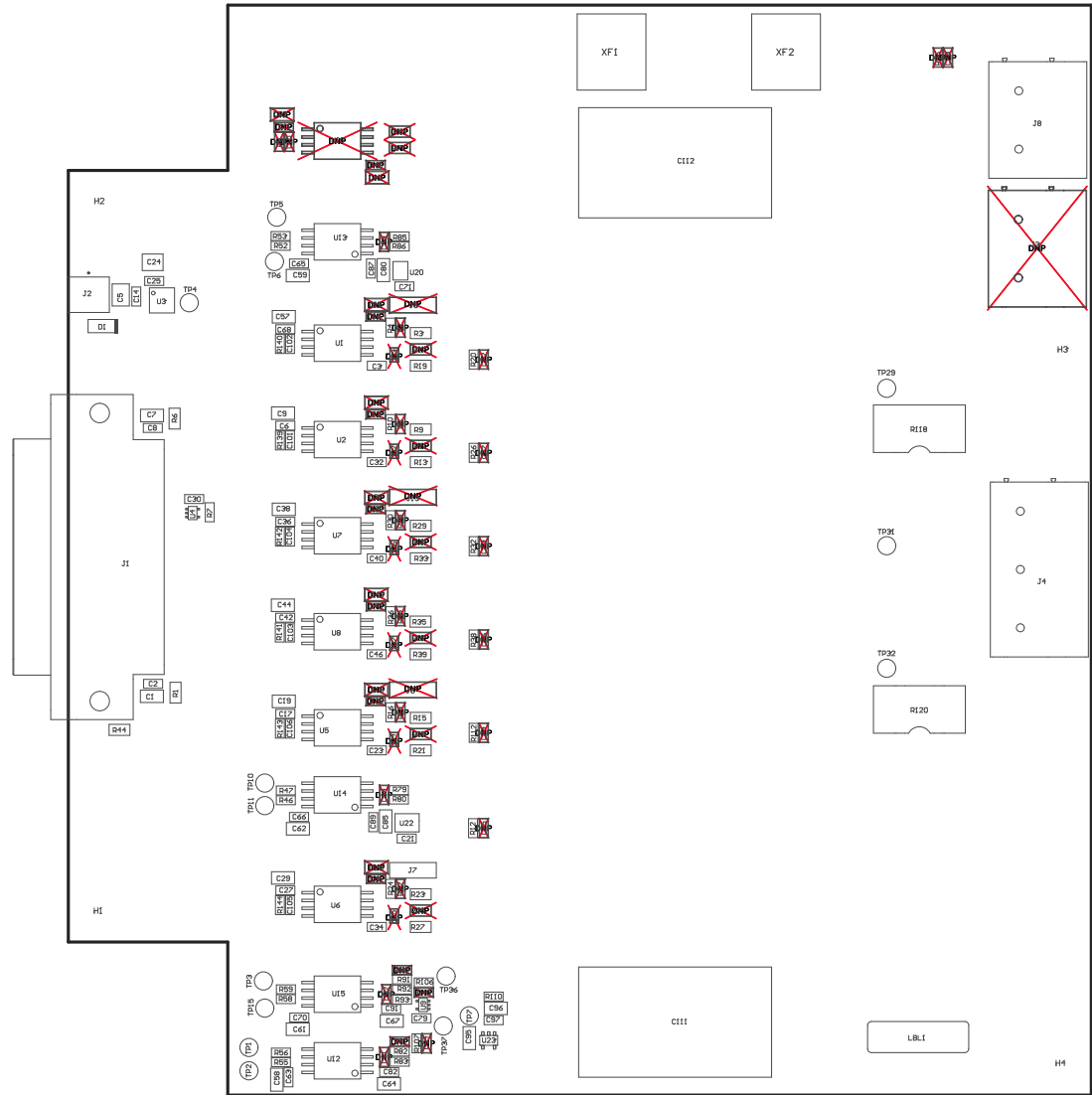
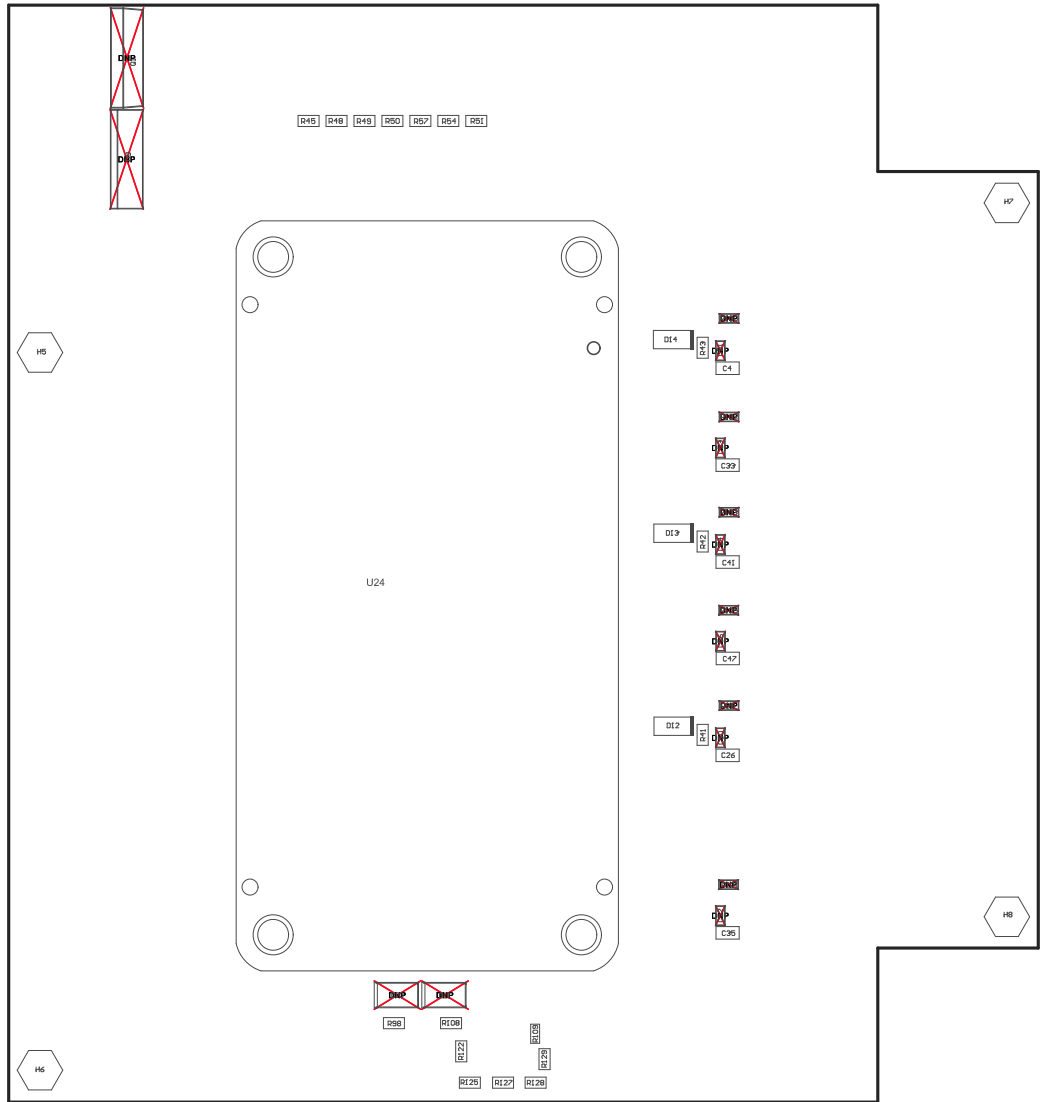


- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be 8 pt font. Text shall be 8 pt font.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: #PC1306C25

ALL PARTWORK VIEWED FROM TOP SIDE	BOARD #:	TIDA-00914	REV:	E1	SUN REV:	Not In VersionControl
LAYER NAME =	MS Assembly Top	TID #:	TIDA-00914			
Top Assembly Drawing	GENERATED :	3/29/2017	7:45:46 PM			TEXAS INSTRUMENTS



COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: ANCI306E25

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDH-00814	REV: E1	SUN REV: Not in version control
LAYER NAME = HS Assembly Bottom	IDNGRE ->		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/25/2017	7:45:46 PM	

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